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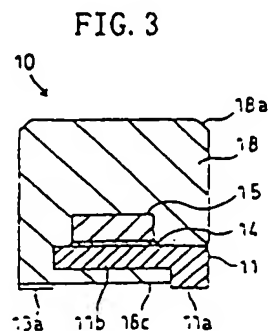
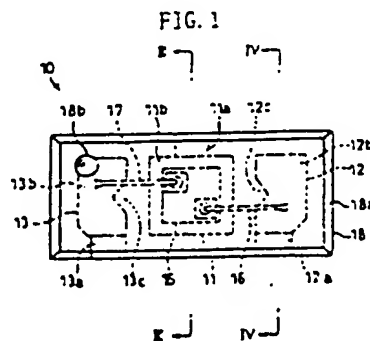
(71) Applicant:
MATSUSHITA ELECTRONICS CORPORATION
Takatsuki-shi, Osaka 569 (JP)

(72) Inventors:
• Takata, Hirofumi
Blizen-shi, Okayama 705 (JP)
• Tanida, Tadashi
Akaiwa-gun, Okayama 709-08 (JP)

(74) Representative: Grünecker, Kinkeldey,
Stockmair & Schwanhäusser
Anwaltssozietät
Maximilianstrasse 58
80538 München (DE)

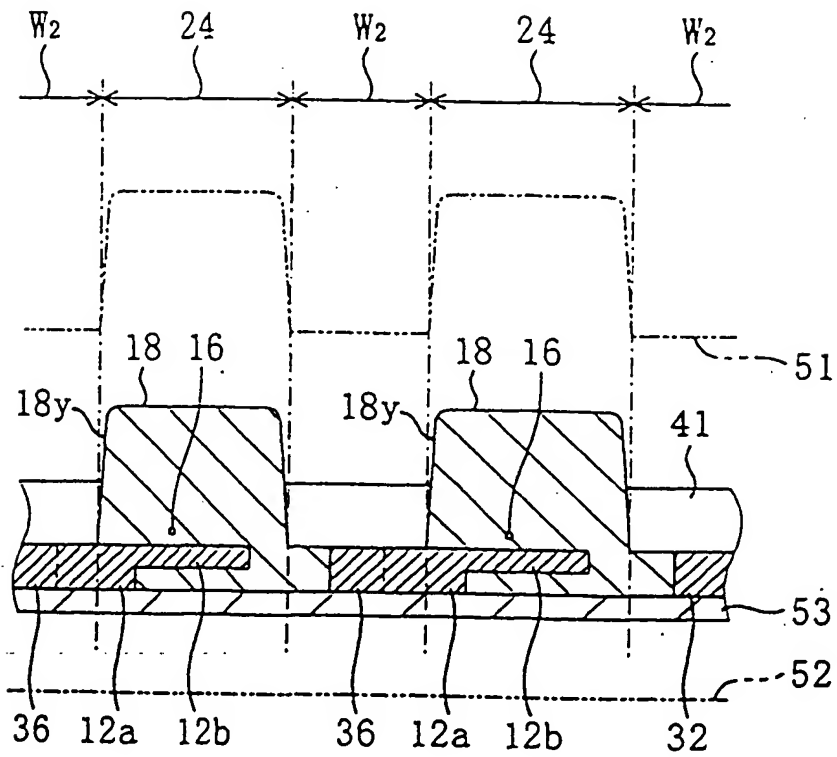
(54) Electronic component, method for making the same, and lead frame and mold assembly for use therein

(57) A lead has a thick part having a thickness of 0.2 mm and a thin part having a thickness of 0.1 mm. The thin part is formed having a greater width than the thick part for preventing the lead from slipping from a resin. A semiconductor chip is fixed on the thin part using a conductive adhesive. A lateral surface of the thick part and a lateral surface of the resin are simultaneously formed by a single cut so that the thick part's lateral surface is located at a lower end area of the resin's lateral surface and these surfaces are exposed forming the same plane. A bottom surface of the thick part projects by from 0.03 mm to 0.05 mm from the resin bottom surface to meet lead stand-off specifications. Thick parts of other leads electrically connected with electrodes on the semiconductor chip with Au wires, are likewise exposed at the resin lateral surface and project from the resin bottom surface. Such arrangements realize high density mounting of electronic components onto a printed board.



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FIG. 21



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